

RD Number: RD100

RD Title: TB67H400ANG Evaluation circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	VM	1	Check terminal	—	—	Check pin		
2	VCC	1	Check terminal	—	—	Check pin		
3	HBMODE	1	Check terminal	—	—	Check pin		
4	VREF	1	Check terminal	—	—	Check pin		
5	OSCM	1	Check terminal	—	—	Check pin		
6	INA1	1	Check terminal	—	—	Check pin		
7	INA2	1	Check terminal	—	—	Check pin		
8	PWMA	1	Check terminal	—	—	Check pin		
9	PWMB	1	Check terminal	—	—	Check pin		
10	INB1	1	Check terminal	—	—	Check pin		
11	INB2	1	Check terminal	—	—	Check pin		
12	TBLKAB	1	Check terminal	—	—	Check pin		
13	RSA	1	Check terminal	—	—	Check pin		
14	RSB	1	Check terminal	—	—	Check pin		
15	OUT_A+	1	Check terminal	—	—	Check pin		
16	OUT_A-	1	Check terminal	—	—	Check pin		
17	OUT_B+	1	Check terminal	—	—	Check pin		
18	OUT_B-	1	Check terminal	—	—	Check pin		
19	GND1	1	Check terminal	—	—	Check pin		
20	GND2	1	Check terminal	—	—	Check pin		
21	GND3	1	Check terminal	—	—	Check pin		
22	GND4	1	Check terminal	—	—	Check pin		
23	GND5	1	Check terminal	—	—	Check pin		
24	GND6	1	Check terminal	—	—	Check pin		
25	RRSA	1	0.22Ω 1W	—	—	Chip resistor		
26	RRSB	1	0.22Ω 1W	—	—	Chip resistor		

27	RVRF1	2	Socket pin	–	–	Socket pin		
28		0	Not mount	–	–	Leaded resistor		✓
29	RVRF2	2	Socket pin	–	–	Socket pin		
30		0	Not mount	–	–	Leaded resistor		✓
31	ROSCM	0	Socket pin	–	–	Socket pin		✓
32		0	5.1kΩ	–	–	Leaded resistor		✓
33		1	5.1kΩ 0.25W	–	–	Resistor		
34	COSCM	0	Socket pin	–	–	Socket pin		✓
35		0	270pF	–	–	Leaded capacitor		✓
36		1	270pF 1000V	–	–	Chip capacitor		
37	CVRF1	1	0.1μF 100V	–	–	Chip capacitor		
38	CVRF2	0	0.1μF 100V	–	–	Chip capacitor		✓
39	CVCC	1	0.1μF 100V	–	–	Chip capacitor		
40	CVM3	0	0.1μF 100V	–	–	Chip capacitor		✓
41	CVM2	1	0.1μF 100V	–	–	Chip capacitor		
42	CVM1	1	100μF 50V	–	–	Electrolytic capacitor		
43	CVDD	0	10μF 10V	–	–	Electrolytic capacitor		✓
44	JP1	1	Pin header 2P	–	–	Jumper		
45		1	Jumper socket	–	–	Jumper Short		
46	JP2	1	Pin header 2P	–	–	Jumper		
47		1	Jumper socket	–	–	Jumper Short		
48	SW1(HBMODE)	1	Pin header 3P	–	–	Jumper		
49		1	Jumper socket	–	–	Jumper Short		
50	SW2(INA1)	1	Pin header 3P	–	–	Jumper		
51		1	Jumper socket	–	–	Jumper Short		
52	SW3(INA2)	1	Pin header 3P	–	–	Jumper		
53		1	Jumper socket	–	–	Jumper Short		
54	SW4(PWMA)	1	Pin header 3P	–	–	Jumper		
55		1	Jumper socket	–	–	Jumper Short		
56	SW5(PWMB)	1	Pin header 3P	–	–	Jumper		
57		1	Jumper socket	–	–	Jumper Short		
58	SW6(INB1)	1	Pin header 3P	–	–	Jumper		
59		1	Jumper socket	–	–	Jumper Short		
60	SW7(INB2)	1	Pin header 3P	–	–	Jumper		

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